

# SOT1181-1

plastic thermal enhanced thin quad flat package; 48 leads;  
exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HTQFP48
<b>Package type industry code</b>	HTQFP48
<b>Package style descriptive code</b>	HTQFP (thermal enhanced thin quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	MS-026
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	4-8-2010

Table 1. Package summary

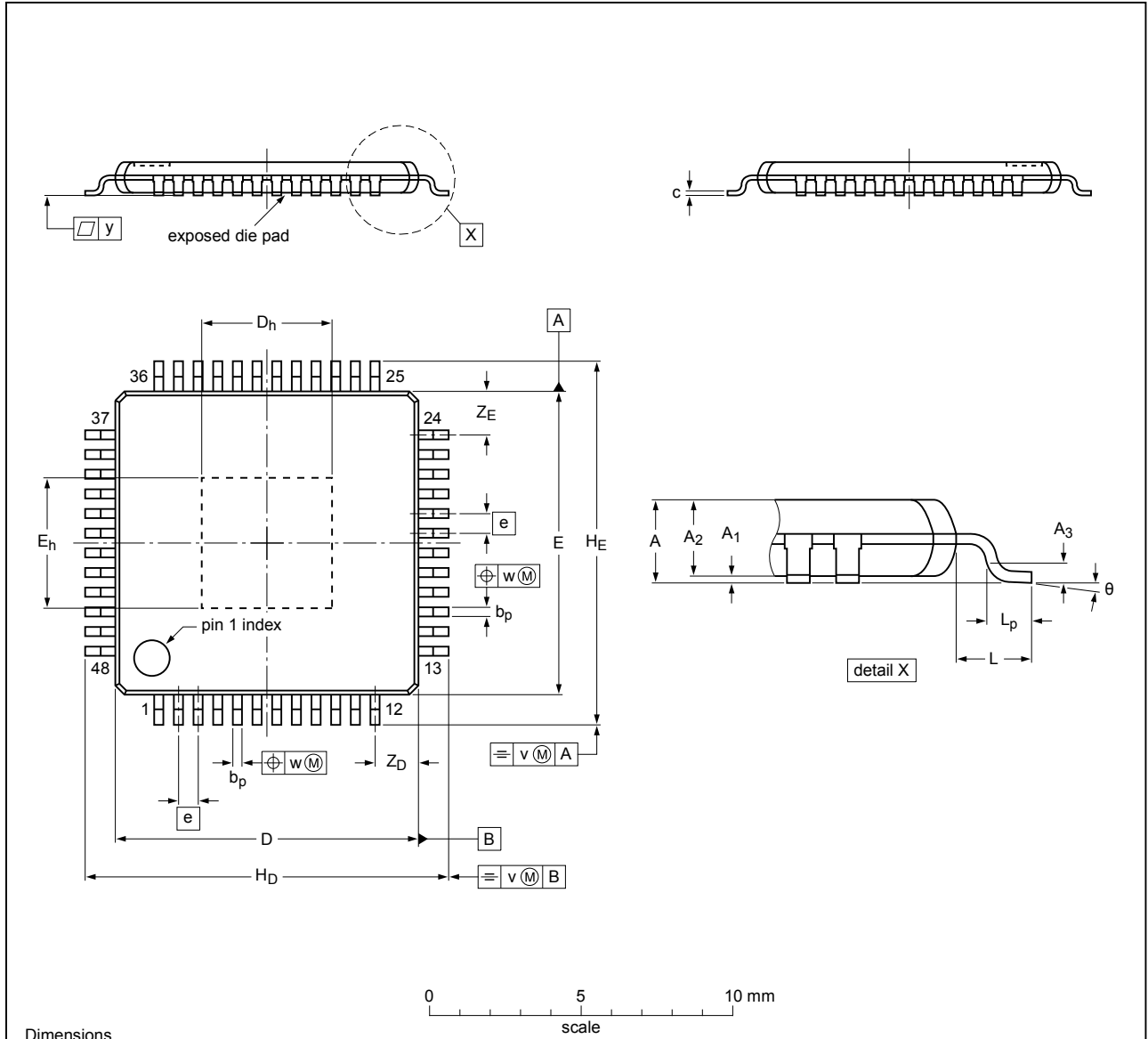
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	[tbd]	1.2	mm
A <sub>2</sub>	package height	0.95	-	1	1.05	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	48	-	



2. Package outline

HTQFP48: plastic thermal enhanced thin quad flat package; 48 leads;  
body 10 x 10 x 1 mm; exposed die pad

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Dimensions

Unit	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
max	1.2	0.125	1.05		0.35	0.18	10.1	4.8	10.1	4.8		12.15	12.15		0.75				1.57	1.57	7°
nom		0.100	1.00	0.25	0.30	0.15	10.0	4.3	10.0	4.3	0.65	12.00	12.00	1	0.60	0.2	0.08	0.1	1.43	1.43	
min		0.050	0.95		0.25	0.12	9.9	3.8	9.9	3.8		11.85	11.85		0.45				1.28	1.28	0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1181-1	---	MS-026	---		10-07-15 10-08-04

Fig. 1. Package outline HTQFP48 (SOT1181-1)

### 3. Legal information

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